

**REMARKS/ARGUMENTS**

The Examiner is thanked for the thorough examination and search of the subject.

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Claims 219-223, 228, 232, 236, 238-242, 250-257, 259, 260 and 262-267 are pending; Claims 220-223, 228, 232, 236, 252 and 263-267 have been currently amended; Claims 1-218, 224-227, 229-231, 233-235, 237, 243-249, 258 and 261 have been canceled. No new matter is believed to have been added.

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Response to Claim Rejections under 35 U.S.C. 102 and 103

Applicants respectfully traverse the rejections for at least the reasons set forth below.

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**Response to Claims 219-223, 228, 232, 236, 238-242, 250-257, 259, 260 and 262-267**

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As previously presented, independent claim 219 is recited below:

219. A chip package comprising:

a substrate;

only one die having a first top surface at a horizontal level;

an adhesive material joining said substrate and said only one die;

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a first insulating layer over said horizontal level, over said only one die, over said substrate and across an edge of said only one die, wherein said first insulating layer comprises a first portion over said only one die and a second portion over said substrate but not over said only one die;

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a patterned circuit layer over said first insulating layer, over said horizontal level, over said only one die and over said substrate, wherein said

patterned circuit layer is connected to said only one die through a first opening  
in said first insulating layer;

an inductor over said horizontal level and over said first insulating layer;

and

5 a second insulating layer on said inductor.

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*Reconsiderations of Claims 219-223, 228, 232, 236, 238-242, 250-257, 259,  
260 and 262-267 rejected under 35 U.S.C. 103(a) as being unpatentable over Tsai  
10 (U.S. Pat. No. 6,180,445) in view of Korman (U.S. Pat. No. 5,959,357) are requested  
based on the following remarks.*

Applicants respectfully assert that the chip package claimed in Claim 219  
patentably distinguishes over the citations by Tsai (U.S. Pat. No. 6,180,445) in view of  
15 Korman (U.S. Pat. No. 5,959,357).

The Examiner considers that Tsai's substrate 10 can be deemed as a die. ~ See  
line 24 on page 2, in the last Office Action mailed Oct. 31, 2008 ~

20 Applicants respectfully traverse the Examiner's opinion because Tsai's substrate  
10 is believed not to be deemed as a die. A die is typically deemed as a small piece  
cut from a semiconductor wafer along scribe lines. Tsai's invention is provided for  
the creation of a high Q inductor that can be applied together with the mounting of flip  
chip semiconductor die on a substrate. ~ See col. 4, lines 28-31, in U.S. Pat. No.  
25 6,180,445 ~ One of ordinary skill in the art is believed to consider that the  
above-mentioned Tsai's flip chip semiconductor die is the whole structure shown in  
Fig. 3, but not only the substrate 10. The substrate 10 is only an underlying portion  
of the above-mentioned flip chip semiconductor die.

30 The Examiner considers that "a first insulating layer (15, 23) .....across an

edge of said only one die, wherein said first insulating layer comprises comprising a first portion over said only one die and a second portion over said substrate but not over said only one die”. ~ See line 25 of page 2 through line 3 of page 3, in the last Office Action mailed Oct. 31, 2008 ~

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Applicants respectfully traverse the Examiner’s opinion because the first insulating layer (15, 23) is not across an edge of the only one die or over the only one die, but within the only one die, i.e. the above-mentioned Tsai’s flip chip semiconductor die. Furthermore, Tsai fails to teach, hint or suggest that the first  
10 insulating layer (15, 23) may have a portion over a substrate joined with the only one die, but not over the only one die.

The Examiner considers that “a patterned circuit layer (19) .....over said only one die and over said substrate”. ~ See lines 3-5 on page 3, in the last Office  
15 Action mailed Oct. 31, 2008 ~

Applicants respectfully traverse the Examiner’s opinion because the patterned circuit layer (19) is not over the only one die, but within the only one die, i.e. the above-mentioned Tsai’s flip chip semiconductor die. Furthermore, Tsai fails to teach,  
20 hint or suggest that the patterned circuit layer (19) may be over a substrate joined with the only one die.

Withdrawal of Rejection under 35 U.S.C. 103(a) to Claim 219 is respectfully requested.

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For at least the foregoing reasons, applicants respectfully submit independent Claim 219 patently distinguishes over the prior art references, and should be allowed. For at least the same reasons, dependent Claims 220-223, 228, 232, 236, 238-242, 250-257, 259, 260 and 262-267 patently define over the prior art as well.

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Conclusion

Some or all of the pending claims are believed to be in condition for Allowance, and that is so requested. Applicant respectfully requests that a timely Notice of  
5 Allowance be issued in this case. Applicant respectfully requests that a timely Notice of Allowance be issued in this case.

Sincerely yours,

10      /Winston Hsu/      Date: 02/26/2009

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Note: Please leave a message in my voice mail if you need to talk to me. (The time in D.C. is 13 hours behind the Taiwan time, i.e. 9 AM in D.C. = 10 PM in Taiwan.)